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004/014

Amendment and Response under 37 C.F.R. 1.116

Applicant: Xiang Dai et al.

Serial No.: 10/612,663

Filed: July 2, 2003

Docket No.: 200308566-1 (H300.211.101)

Title: SUPPORTING A CIRCUIT PACKAGE INCLUDING A SUBSTRATE HAVING A SOLDER COLUMN ARRAY

IN THE CLAIMS

Please cancel claims 17 and 20 without prejudice.

Please amend claims 8, 10, 15, and 23-28 as follows:

1-7. (Cancelled)

8. (Currently Amended) An assembled electronic component system comprising:
a printed circuit board;
an integrated circuit package, in both a first, initial assembled state of the assembled system and a second, final assembled state of the assembled system, including a substrate having a solder column array connecting the integrated circuit package directly to the printed circuit board and a lid, the lid including an extended portion that extends directly from the substrate outwardly over an edge of the substrate;
a plurality of supports disposed directly on the printed circuit board with each support disposed at each corner of the integrated circuit package, underneath the lid of the integrated circuit package between the lid and the printed circuit board, and each support including a body and a pair of wings extending from the body to be substantially perpendicular to each other for contacting the edges of the substrate of the integrated circuit package and the wings of the support being sized and shaped to extend underneath the extended portion of the lid of the integrated circuit package, wherein the body is sized and shaped to extend outwardly in a direction generally opposite from the wings to be exposed relative to, and not in contact with the extended portion of the lid, wherin the wings of the support are sized and shaped to enable a gap between the extended portion of the lid of the integrated circuit package and the wings of the supports in a first initial-assembled state of the assembled system, and wherin the wings of the support are sized and shaped and to enable contact between the extended portion of the lid of the integrated circuit package and the wings of the supports without the gap in a second, final assembled state of the assembled system; and wherein each support includes a body and a pair of wings extending from the body to be substantially perpendicular to each other for contacting the edges of the substrate of the integrated circuit package, the support sized and shaped to cause the wings to be underneath and in contact with the extended portion of the lid in the second, final assembled state of the system and the body

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sized and shaped to extend outwardly in a direction generally opposite from the wings to be exposed relative to, and not in contact with the extended portion of the lid;

a compressive force mechanism applying a compressive force on the integrated circuit package against the printed circuit board in both the first, initial assembled state of the assembled system and the second, final assembled state of the assembled system, with the compressive force translated from the integrated circuit package to the printed circuit board through only the solder column array in the first, initial assembled state of the assembled system and translated from the integrated circuit package to the printed circuit board through both the solder column array and the supports via the extended portion of the lid in the second, final assembled state of the assembled system; and

a heat sink secured on top of the lid of the integrated circuit package via the compressive force in both the first initial state of the assembled system and the second, final assembled state of the assembled system, the lid being separate from and independent of the heat sink.

9. (Cancelled).

10. (Currently Amended) The system of claim 8 wherein the solder column array has a first height in the first initial assembled state of the assembled system and a second height in the second, final assembled state of the assembled system, the second height being less than the first height.

11-12. (Cancelled).

13. (Previously Presented) The system of claim 8 wherein each support includes a detent and the printed circuit board includes a plurality of holes shaped and sized for receiving the detent of the supports so that each support is secured to the printed circuit board upon insertion of the detent of the support into the hole of the printed circuit board.

14. (Original) The system of claim 8 wherein each support is made from at least one of a plastic material, a metal material, and a composite material, with the material having a

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coefficient of thermal expansion that is substantially the same as a coefficient of thermal expansion of the substrate and the solder column array.

15. (Currently Amended) An electronic component system comprising:
means for carrying circuit components;
means for performing circuit functions including:
 a substrate;
 first means for directly electrically connecting and directly mechanically connecting the substrate to the means for carrying circuit components; and
 second means, disposed on top of the substrate and extending from the substrate outwardly beyond the substrate, for translating a compressive load to the means for carrying circuit components;
means for applying the compressive load to force the means for performing circuit functions against the means for carrying circuit components through the first means; and
 support means, removably attachable directly on the means for carrying circuit components, for interposing between the second means for translating and the means for carrying circuit component and for mechanically connecting the second means for translating to the means for carrying circuit components, the support means configured to enable a gap between the second means for translating and the support means in a first initial assembled state of the assembled system while the compressive load is applied, and to enable translation of the compressive force from the second means for translating via the support means to the means for carrying circuit components without the gap in a second final assembled state of the assembled system while the compressive load is applied.
16. (Previously Presented) The system of claim 15 wherein the means for carrying circuit components comprises a printed circuit board and wherein the means for performing circuit functions comprises an integrated circuit package that includes the substrate and the second means for translating.

17-20. (Canceled)

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21. (Previously Presented) The system of claim 8 wherein the body of the support is sized, shaped, and positioned relative to the integrated circuit package to be secured relative to the printed circuit board via a fastener extending through the printed circuit board and into the body of the support while the wings of the support are in position below and in contact with the extended portion of the lid of the integrated circuit package.

22. (Canceled)

23. (Currently Amended) The system of claim 8 wherein the supports are configured to be mechanically fastened to the printed circuit board without an adhesive and configured to support the lid of the integrated circuit package in the second final assembled state of the assembled system without an adhesive between the lid of the integrated circuit package and the support.

24. (Canceled)

25. (Previously Presented) The system of claim 8, wherein the electronic component system comprises a computer system.

26. (Currently Amended) The system of claim 16 wherein the first means for directly electrically connecting and directly mechanically connecting comprises a solder column array connecting the integrated circuit package to the printed circuit board, and the solder column array has a first height in the first initial assembled state of the assembled system and a second height, less than the first height, in the second final assembled state of the assembled system.

27. (Currently Amended) The system of claim 26 wherein the support means for mechanically connecting comprises:

a plurality of supports with one support disposed at each corner of the integrated circuit package underneath the lid of the integrated circuit package, and each support sized and shaped to enable the gap between the lid of the integrated circuit package and the

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supports in the first, initial assembled state of the assembled system, and to enable contact between the lid of the integrated circuit package and the supports without the gap in the second, final assembled state of the assembled system.

28. (Currently Amended) An assembled electronic component system comprising:

a printed circuit board;

an integrated circuit package including a substrate having a solder column array connecting the integrated circuit package to the printed circuit board and a lid, the lid including an extended portion that extends outwardly from the substrate over an edge of the substrate;

a plurality of supports disposed on the printed circuit board with each support disposed at each corner of the integrated circuit package ~~underneath the lid of the integrated circuit package between the lid and the printed circuit board, and with each support comprising a pair of wing portions that are generally perpendicular to each other and joined together at one end to define a corner, each wing portion of the respective supports extending underneath the extended portion of the lid of the integrated circuit package between the lid and the printed circuit board, and each wing portion of the respective supports being sized and shaped to leave a gap between the extended portion of the lid of the integrated circuit package and the wing portions of the respective supports in a first initial assembled state of the assembled system, and the wing portions of the respective supports being sized and shaped to contact and support the extended portion of the lid of the integrated circuit package via the wing portions of the without the gap in a second, final assembled state of the assembled system;~~

a single band sized and shaped to surround and contact all of the respective supports and apply a lateral force against the wing portions and the corners of the respective supports to secure the respective supports in position underneath the extended portion of lid of the integrated circuit package and to maintain the respective supports in position relative to the printed circuit board;

a compressive force mechanism applying a compressive force on the integrated circuit package against the printed circuit board in both the first initial assembled state of the assembled system and the second, final assembled state of the assembled system, with the compressive force translated through only the solder column array in the first initial

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assembled state of the assembled system and translated through both the solder column array and the respective supports via the extended portion of the lid in the second, final assembled state of the assembled system; and

a heat sink secured on top of the lid of the integrated circuit package via the compressive force with the heat sink being separate from and independent of the lid of the integrated circuit package , wherein the solder column array maintains electrical and mechanical connection between the printed circuit board and the substrate in both the first initial assembled state of the assembled system and the second, final assembled state of the assembled system, and the solder column array has a first height in the first initial assembled state of the assembled system and the solder column array has a second height, less than the first height, in the second, final assembled state of the assembled system.

29. (Previously Presented) The system of claim 28, where in the electronic component system comprises a computer system.